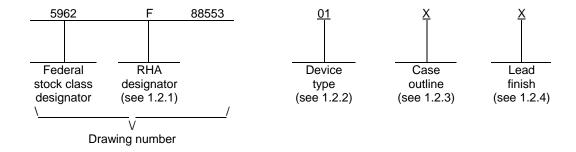
LTR					I	DESCR	RIPTIO	N					DA	ATE (YF	R-MO-I	DA)		APPF	ROVED	APPROVED	
А	limits	Add case outlines T and U. Add vendors CAGE 69210 and U4637 limits for line regulation, load regulation tests and standby current d temperature. Add temperature testing limit for Ripple rejection test.				ırrent d	rain tes		89-08-08		M. A. FRYE										
В	Add o	case ou	ıtline 2	. Edito	rial cha	anges t	hrough	out.						92-0	3-30			M. A.	FRYE		
С	Add o U463	case ou 7 to U3	ıtline N 3158. I	l. Rem Editoria	ove ve Il chan	ndor Ca ges thro	AGE 48 oughou	3726. ( it.	Change	e vendo	r CAGI	E		96-0	1-17			M. A.	FRYE		
D		CAGE 2 e 1, and				ne M.	Make o	change	s to 1.2	2.2, 1.3,	1.4, ta	ıble I,		99-1	2-01			R. M	ONNIN		
Е	Add r	adiatio	n hardı	ness re	quirem	ents	- ro							00-0	2-17			R. M	ONNIN		
F		chang , 1.3, fi					ase out	lines 4	and 5.	Make	change	es to		02-0	2-11			R. M	ONNIN		
G	Add a	a footno	ote to tl . Make	he case correc	outlin tions to	e U, T( packa	D-257 p	ackago e desci	e as sp riptions	ecified under	under 1.2.2.	1.2.2 - ro		05-0	2-04			R. M	ONNIN		
Н	For c	ase ou	tline "T r figure	" only, 1 r	add a f	ootnote	e <u>1</u> / und	der 1.2.	.3 and ı	make c	hange	to		06-0	1-10			R. M	ONNIN		
THE ORIGINA	L FIRST	SHEE	T OF T	THIS DI	RAWIN	IG HAS	S BEEN	I REPL	ACED.												
REV SHEET REV SHEET	H 15	SHEE H	T OF T			IG HAS					Н	Н	н	н	Н	Н	Н	Н	H	н	
REV SHEET REV	H 15	Н	Н	REV	,	IG HAS	S BEEN	REPL	ACED.	H 4	H 5	H 6	H 7	H 8	H 9	H 10	H 11	H 12	H 13	H 14	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A	H 15	H 16	Н	REV SHE	EET		H 1	Н	Н	Н	5	6 EFEN	7 SE S	8 UPPL	9 <b>Y CE</b>	10	11 COL	12 .UMB	13		
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A	H 15	H 16	Н	REV SHE PREI JO	PAREI SEPH	D BY A. KER	H 1	Н	Н	Н	5	6 EFEN	7 SE SI	8	9 Y CE	10 NTER O 432	11 R COL 218-3	12 .UMB	13		
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A  STA MICRO DRA  THIS DRAWII FOR L	H 15	H 16 CUIT G	H 17	REV SHE PREI JO	PAREI SEPH CKED ARLES	D BY A. KER BY S E. BE	H 1	Н	Н	H 4	DI DI	EFEN CC	SE SI DLUM http	8 UPPL IBUS,	Y CE, OHIO	NTER O 432 cc.dl	11 R COL 218-3: a.mil	12 LUMB 990	us OLT		
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A  STA MICRO DRA  THIS DRAWII FOR L	H 15 COCIRCO AWING IS A JSE BY ARTMEN INCIES CO	H 16 CUIT G VAILABALL TS DF THE	H 17	REV SHE PREI JO CHE CH/	PAREI SEPH CKED ARLES	D BY A. KER BY S.E. BE. D BY A. FRY	H 1	H 2	Н	H 4	DI DI	EFEN CC	SE SI DLUM http	UPPLIBUS, D://ww	Y CE, OHIO	NTER O 432 cc.dl	11 R COL 218-3: a.mil	12 LUMB 990	us OLT		
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A  STA MICRO DRA  THIS DRAWII FOR L DEPA AND AGE DEPARTME	H 15 COCIRCO AWING IS A JSE BY ARTMEN INCIES CO	H 16 CUIT G VAILAE ALL TS DF THE	H 17	REV SHE PREI JO CHE CH/	PAREI SEPH CKED ARLES	D BY A. KER BY S E. BE: D BY A. FRY APPRO 88-0	H 1 SORE	H 2	Н	H 4	DI DI	6 CA	SE SI DLUM http	BUPPLIBUS, DELINE, CED, I	Y CE, OHIO	NTER O 432 Sec.dl	11 R COL 218-3: a.mil	12 -UMB 990 15 VO	13 OLT		

- 1. SCOPE
- 1.1 <u>Scope</u>. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.
  - 1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



- 1.2.1 RHA designator. RHA marked devices shall meet the MIL-PRF-38535 or MIL-PRF-38535, Appendix A specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
  - 1.2.2 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	7815A	Positive regulator, 15 volt fixed

1.2.3 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
M	See figure 1	3	Power surface mount
N	CBCC2-N3	3	Bottom terminal chip carrier
T <u>1</u> /	See figure 1	3	TO-257 single row flange mount and glass sealed
U <u>1</u> /	See figure 1	3	TO-257 single row flange mount with isolated tab and glass sealed
Χ	See figure 1	3	TO-39 can
Υ	See figure 1	2	TO-3 flange mount
Z	MBFM4-P2	2	TO-66 flange mount
2	CQCC1-N20	20	Square leadless chip carrier
4	See figure 1	3	Flange mount, glass sealed, with gull wings
5	CBCC1-N3	3	Bottom terminal chip carrier

1.2.4 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

1/ For outline letters T and U, CAGE 34333 manufacturers the TO-257 package with ceramic seal.

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# 1.3 Absolute maximum ratings. Input voltage: Power dissipation (PD): $T_C = +25^{\circ}C$ : Cases X and 2 ...... 2 W Case Y ...... 20 W Cases M, T, U, and Z ...... 3.0 W Case Y ...... 4.3 W Case 4 ...... 1.7 W Case 5 ...... 1.3 W Storage temperature range -65°C to +150°C Lead temperature (soldering, 10 seconds) ...... +300°C Junction temperature (T<sub>J</sub>)......+150°C 3/ Thermal resistance, junction-to-case ( $\theta_{JC}$ ): Case M...... 6.7°C/W Case U 4.2°C/W Case Y ...... 3°C/W Case 5 ...... 3.6°C/W Thermal resistance, junction-to-ambient (θ μ): 1.4 Recommended operating conditions. Ambient operating temperature range (T<sub>A</sub>).....--55°C to +125°C 1.5 Radiation features:

These parts may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions specified in MIL-STD-883, method 1019, condition A.

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The 50 volt input rating refers to the ability of the regulator to withstand high line or transient conditions without damage. Since the regulator's maximum current capability is reduced, the output may fall out of regulation at high input voltages under nominal loading.

<sup>3/</sup> The device is protected by thermal shutdown circuit which is designed to turn off the output transistor whenever the device junction temperature is in excess of +150°C.

#### 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

#### DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

#### DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

#### DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at http://assist.daps.dla.mil/quicksearch/ or http://assist.daps.dla.mil or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

#### 3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
  - 3.2.1 <u>Case outlines</u>. The case outlines shall be in accordance with 1.2.2 herein and figure 1.
  - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.
  - 3.2.3 Radiation exposure circuit. The radiation exposure circuit shall be as specified on figure 3.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

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	Т	ABLE I. Electr	ical performance	e characteristic	<u>S</u> .				
Test	Symbol	Conditions $\underline{1}/\underline{2}/\underline{3}/$ -55°C $\leq$ T <sub>A</sub> $\leq$ +125°C unless otherwise specified		Group A subgroups	Device type	Limits		Unit	
						Min	Max	(	
Output voltage	Vout	T <sub>A</sub> = +25°C		1	01	14.8	15.2	V	
			M,D,P,L,R,F	1		14.8	15.2		
		V <sub>IN</sub> = 18.5 V	to 30 V <u>4</u> /	1,2,3		14.6	15.4		
			M,D,P,L,R,F	1	1	14.6	15.4		
Line regulation 5/6/	V <sub>RLINE</sub>	V <sub>IN</sub> = 17.5 V	to 30 V,	1	01		20	mV	
		-55°C ≤ T <sub>J</sub> ≤	-55°C ≤ T <sub>J</sub> ≤ +125°C	2,3 R,F 1			50		
			M,D,P,L,R,F		1		20		
		V <sub>IN</sub> = 20 V to 26 V,		1	1		15	1	
		-55°C ≤ T <sub>J</sub> ≤	+125°C	2,3	=		25		
			M,D,P,L,R,F 1			15	1		
Load regulation 5/	VRLOAD	$I_{O} = 5.0 \text{ mA}$ -55°C \le T <sub>J</sub> \le		1	01		35	mV	
			M,D,P,L,R,F	1			35	1	
		I <sub>O</sub> = 5.0 mA	to 1.0 A, <u>7</u> /	2.3			75		

 $\text{-}55^{\circ}C \leq T_{J} \leq \text{+}125^{\circ}C$ 

 $-55^{\circ}C \le T_{J} \le +125^{\circ}C$ 

 $\text{-}55^{\circ}C \leq T_{J} \leq \text{+}125^{\circ}C$ 

 $I_0 = 250 \text{ mA to } 750 \text{ mA}, \ \underline{7}/$ 

 $I_0 = 5.0 \text{ mA to } 500 \text{ mA}, \ 8/$ 

M,D,P,L,R,F

M,D,P,L,R,F

2,3

1

2,3

1

1

2,3

1

2,3

1

01

Н

75

21

45

21

50

75

6.0

6.5

6.0

mΑ

5

See footnotes at end of table.

Standby current drain

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ISCD

TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test			ymbol Conditions $\underline{1}/\underline{2}/\underline{3}/$ -55°C $\leq$ T <sub>A</sub> $\leq$ +125°C unless otherwise specified		Device type	Liı	mits	Unit
			·			Min	Max	
Standby current drain change with line	ΔI <sub>SCD</sub> (line)	V <sub>IN</sub> = 18.5 V to 30 V		1,2,3	01		0.8	mA
			M,D,P,L,R,F	1	j		0.8	
Standby current drain change with load	ΔI <sub>SCD</sub> (load)	I <sub>O</sub> = 5.0 mA t	o 1000 mA	1,2,3	01		0.5	mA
			M,D,P,L,R,F	1	]		0.5	
Dropout voltage	V <sub>DO</sub>	$\Delta V_{OUT} = 100$ $I_{O} = 1.0 \text{ A, T}_{A}$		1	01		2.5	V
			M,D,P,L,R,F	1			2.5	
		$\Delta V_{OUT} = 100 \text{ mV}, \ 8/$ $I_{O} = 500 \text{ mA}, T_{A} = +25 ^{\circ}\text{C}$		1			2.5	
Peak output current	I <sub>O(PK)</sub>	T <sub>A</sub> = +25°C	<u>7</u> /	1	01	1.5	3.3	А
			M,D,P,L,R,F	1		1.5	3.3	_
		T <sub>A</sub> = +25°C	<u>8</u> /	1		0.5	1.7	
Short circuit current 9/	los	V <sub>IN</sub> = 35 V 5	<u>:/</u>	1	01		1.2	Α
				2,3			2.8	
			M,D,P,L,R,F	1			1.2	
		V <sub>IN</sub> = 35 V <u>8</u> /		1		0.7		
				2,3			2.0	
Ripple rejection	ΔV <sub>IN</sub> /	f = 120 Hz, Δ	f = 120 Hz, ΔV <sub>IN</sub> = 10 V		01	54		dB
	ΔVουτ			5,6 <u>8</u> /		52		
			M,D,P,L,R,F	4		54		
Output noise voltage 10/	NO	f = 10  Hz to  1 $T_A = +25^{\circ}\text{C}$	100 kHz,	7	01		40	μV / V rms
Long term stability 10/	ΔV <sub>OUT</sub> /	$T_A = +25^{\circ}C$ , $t = 1,000 \text{ hou}$	ırs	7	01		150	mV

See footnotes at end of table.

STANDARD
MICROCIRCUIT DRAWING

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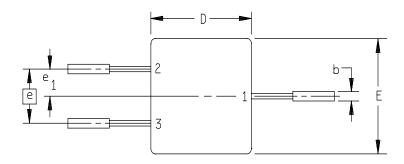
SIZE <b>A</b>		5962-88553
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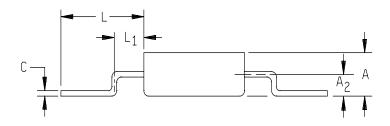
### TABLE I. Electrical performance characteristics - Continued.

- Devices supplied to this drawing have been characterized through all levels M, D, P, L, R, F of irradiation. However, this device is only tested at the "F" level. Pre and Post irradiation values are identical unless otherwise specified in table I. When performing post irradiation electrical measurements for any RHA level, T<sub>A</sub> = +25°C.
- These parts may be dose rate sensitive in a space environment and may demonstrate enhanced low dose rate effects. Radiation end point limits for the noted parameters are guaranteed only for the conditions specified in MIL-STD-883, method 1019, condition A.
- Unless otherwise specified, V<sub>IN</sub> = 23 V and I<sub>O</sub> = 500 mA for cases M, N, T, U, Y, Z, 4, and 5, V<sub>IN</sub> = 23 V and I<sub>O</sub> = 100 mA for cases X and 2. Maximum test current for cases X and 2 is 500 mA.
- $\underline{4}/$  For cases X and 2:  $I_O = 5$  mA to 500 mA,  $P \le 2$  W. For case Y:  $I_O = 5$  mA to 1.0 A,  $P \le 20$  W. For cases M, N, T, U, Z, 4, and 5:  $I_O = 5$  mA to 1.0 A,  $P \le 15$  W.
- 5/ All measurements except output noise voltage and ripple rejection are made at constant junction temperature and with low duty cycle.
- 6/ Minimum load current for full line regulation is 5.0 mA.
- <u>7</u>/ For cases M, N, T, U, Y, Z, 4, and 5 only.
- 8/ For cases X and 2 only.
- 9/ Short circuit protection is only assured up to  $V_{IN} = 35 \text{ V}$ .
- 10/ If not tested, shall be guaranteed to the limits specified in table I herein.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.
- 3.5.1 <u>Certification/compliance mark</u>. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
  - 3.8 Notification of change. Notification of change to DSCC-VA shall be required for any change that affects this drawing.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

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## Case outline M





Symbol	Inches		Millim	neters
	Min	Max	Min	Max
Α	.160		4.06	
A <sub>2</sub>	.080		2.03	
b		.035		0.89
С	.020		0.51	
D		.425		10.8
Е		.425		10.8
е	.200	BSC	5.08 BSC	
e <sub>1</sub>	.100	BSC	2.54	BSC
L	.350		8.89	
L <sub>1</sub>		.135		3.43

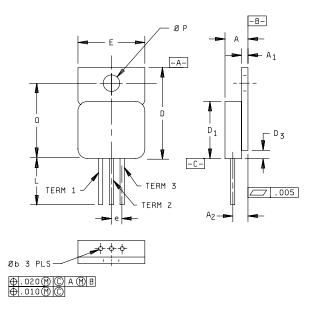
## NOTES:

- The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
- 2. Metric equivalents are given for general information only.
- 3. Three leads.

FIGURE 1. Case outlines.

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## Case outlines T and U



<u>Inches</u>	mm
.005	0.13
.010	0.25
.020	0.51

Letter	Inc	hes	Millim	eters
	Min	Max	Min	Max
Α	.190	.200	4.83	5.08
A1	.035	.045	0.89	1.14
A2	.120	BSC	3.05	BSC
φb	.025	.035	0.64	0.89
D	.645	.665	16.38	16.89
D1	.410	.430	10.41	10.92
D3	.000	.065	0.00	1.65
е	.100 BSC		2.54 BSC	
E	.410	.422	10.41	10.71
L	.500	.750	12.70	19.05
0	.527	.537	13.39	16.64
φP	.140	.150	3.56	3.81

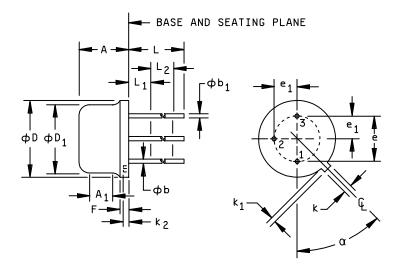
### NOTE:

- 1. The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
- 2. For case outlines T and U only, CAGE 34333, the ceramic seal that protrudes from the seating plane is not to be considered in overall package dimensions. The ceramic seal protrusion is considered uncontrolled within an area 30 mils from the seating plane.

FIGURE 1. Case outline - Continued.

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#### Case outline X



Symbol	Inc	hes	Millimeters		Notes
	Min	Max	Min	Max	
Α	.165	.185	4.19	4.70	
$A_1$	.100	BSC	2.54	BSC	
фЬ	.016	.019	0.41	0.48	2
φb <sub>1</sub>	.016	.021	0.41	0.53	2
φD	.335	.370	8.51	9.40	
φD <sub>1</sub>	.305	.335	7.75	8.51	
е	.200 BSC		5.08 BSC		4
e <sub>1</sub>	.100	BSC	2.54 BSC		4
F		.050		1.27	
k	.028	.034	0.71	0.86	
k <sub>1</sub>	.029	.045	0.74	1.14	3
$k_2$	.009	.041	0.23	1.04	
L	.500		12.70		
L <sub>1</sub>		.050		1.27	
$L_2$	.250		6.35		
α	45°	T.P	45°	T.P.	4

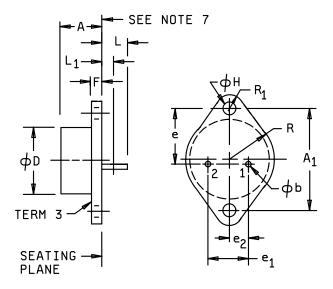
## NOTES:

- 1. The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
- (All leads) φb applies between L<sub>1</sub> and L<sub>2</sub>. φb<sub>1</sub> applies between the L<sub>2</sub> and .500 inch
  (12.70 mm) from the reference plane. Diameter is uncontrolled in L<sub>1</sub> and beyond .500 inch
  (12.70 mm) from the reference plane.
- 3. Measured from the maximum diameter of the product.
- 4. Leads having a maximum diameter of .019 inch (0.48 mm) measured in gauging plane .054 inch (1.37 mm) + .001 inch (0.03 mm) .000 inch (0.00 mm) below the base plane of the product shall be within .007 inch (0.18 mm) of their true position relative to a maximum width tab.
- 5. The relative product may be measured by direct methods or by gauge.

FIGURE 1. Case outline - Continued.

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#### Case outline Y



Symbol	Incl	nes	Millim	neters	Notes
	Min	Max	Min	Max	
Α	.250	.450	6.35	11.43	
A <sub>1</sub>	1.177	1.197	29.90	30.40	
фЬ	.038	.043	.97	1.09	3,7
φD		.875		22.22	
е	.655	.675	16.64	17.14	5
e <sub>1</sub>	.420	.440	10.67	11.16	5
$e_2$	.205	.225	5.21	5.72	
F	.060	.135	1.52	3.43	
φН	.151	.161	3.84	4.09	5,6
L	.312	.500	7.92	12.70	4
L <sub>1</sub>		.050		1.27	3,4
R	.495	.525	12.57	13.34	
R₁	.131	.188	3.33	4.78	

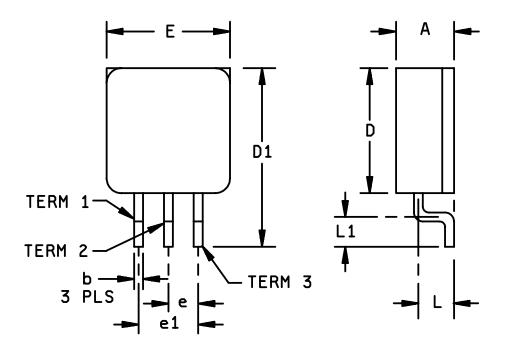
## NOTES:

- 1. The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
- 2. (Two leads) φb applies between L<sub>1</sub> and .500 inch (12.70 mm) from the seating plane. Diameter is uncontrolled in L<sub>1</sub>, and beyond .500 inch (12.70 mm) from the seating plane.
- 3. Two leads.
- 4. Two holes.
- 5. Two holes located at true position within diameter .010 inch (0.25 mm).
- 6. Leads having a maximum diameter of .043 inch (1.09 mm) measured in gauging plane .054 inch (1.37 mm) + .001 inch (0.03 mm) .000 inch (0.00 mm) below the base plane shall be located at true position within diameter .014 inch (0.36 mm).
- 7. The mounting surface of the header shall be flat to convex within .003 inch (0.08 mm) inside a .930 inch (23.62 mm) diameter circle on the center of the header and flat to convex within .006 inch (0.15 mm) overall.

FIGURE 1. Case outline - Continued.

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DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL <b>H</b>	SHEET 11

## Case outline 4



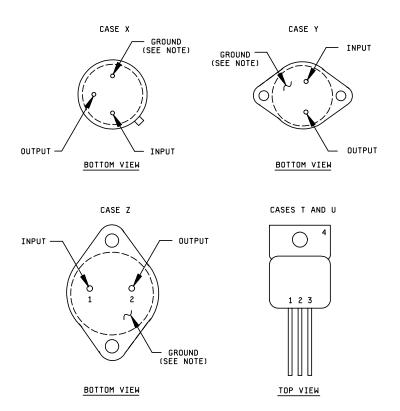
Symbol	Inches		Millim	neters
	Min	Max	Min	Max
Α	.190	.210	4.83	5.33
b		.030		0.76
D	.410	.430	10.41	10.92
D1	.580	.610	14.73	15.49
е		.100		2.54
e1		.200		5.08
E	.410	.420	10.41	10.67
L1	.090	.110	2.29	2.79
Ĺ	.115	.125	2.92	3.18
N	3	3	;	3

## NOTE:

The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. Case outline - Continued.

# STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990 SIZE A SP62-88553 REVISION LEVEL H 12



NOTE: Case is connected to ground.

FIGURE 2. Terminal connections.

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Device type	01						
Case outlines	М	N	Т	U	2	4	5
Terminal number		Terminal symbol					
1	OUTPUT	OUTPUT	INPUT	INPUT	NC	INPUT	OUTPUT
2	ADJUST	INPUT	GND	GND	V <sub>IN</sub>	GND	INPUT
3	INPUT	GND	OUTPUT	OUTPUT	NC	OUTPUT	GND
4	ISOLATED (CASE)		GND	NC	NC		
5					NC		
6					NC		
7					GND		
8					NC		
9					NC		
10					Vout		
11					NC		
12					Vout		
13					NC		
14					NC		
15					V <sub>OUT</sub> SENSE		
16					NC		
17					V <sub>IN</sub>		
18					NC		
19					NC		
20					NC		

# NOTES:

NC = No connection

For case outline 2 normal operation, the  $V_{\mbox{OUT}}$  SENSE pin must be connected externally to the load.

FIGURE 2. <u>Terminal connections</u> – Continued.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-88553
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL <b>H</b>	SHEET 14

# Case outline U

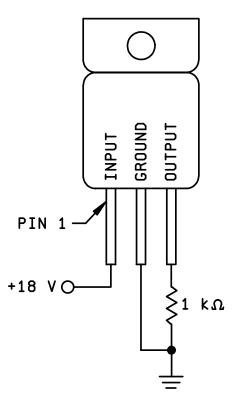


FIGURE 3. Radiation exposure circuit.

STANDARD MICROCIRCUIT DRAWING DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		5962-88553
		REVISION LEVEL <b>H</b>	SHEET <b>15</b>

#### 4. VERIFICATION

- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - Subgroups 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.
  - 4.3.2 Groups C and D inspections.
    - a. End-point electrical parameters shall be as specified in table II herein.
    - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
      - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
      - (2)  $T_A = +125^{\circ}C$ , minimum.
      - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.3.3 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels shall be as specified in MIL-PRF-38535 or MIL-PRF-38535, Appendix A. End-point parameters shall be as specified in table II herein.
- 4.3.3.1 <u>Total dose irradiation testing</u>. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019, condition A and as specified herein.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1, 2, 3, 4 <u>1</u> /
Group A test requirements (method 5005)	1, 2, 3, 4, 5, 6, 7 <u>2</u> /
Groups C and D end-point electrical parameters (method 5005)	1
Group E end-point electrical parameters (method 5005)	1, 4

- 1/ PDA applies to subgroup 1.
- 2/ Subgroups 5, 6, and 7, if not tested, shall be guaranteed to the limits specified in table I herein.

#### 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

## 6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0547.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD  MICROCIRCUIT DRAWING  DEFENSE SUPPLY CENTER COLUMBUS  COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		5962-88553
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## STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 06-01-10

Approved sources of supply for SMD 5962-88553 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DSCC maintains an online database of all current sources of supply at <a href="http://www.dscc.dla.mil/Programs/Smcr/">http://www.dscc.dla.mil/Programs/Smcr/</a>.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8855301MA	<u>3</u> /	OM1815NSM/883B
5962-8855301NA	21845	SDP7815ANMD
	<u>3</u> /	OM1815NMM
5962-8855301NB	<u>3</u> /	OM1815NMM
5962-8855301TA	U3158	IP7815AG-DESC
	21845	SDP7815ATMD
	34333	SG7815AG/883B
	<u>3</u> /	UC7815AG/883B
	<u>3</u> /	OM7815AH/883B
5962-8855301UA	U3158	IP7815AIG-DESC
	21845	SDP7815AUMD
	34333	SG7815AIG/883B
	<u>3</u> /	FM815S7
	<u>3</u> /	UC7815AIG/883B
	<u>3</u> /	OM7815AIH/883B
5962-8855301XA	U3158	IP78M15AH-DESC
	34333	SG7815AT/883B

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8855301YA	U3158	IP7815AK-DESC
	34333	SG7815AK/883B
	<u>3</u> /	UC7815AK/883B
	<u>3</u> /	OM7815NKM
5962-8855301ZA	U3158	IP7815AR-DESC
	21845	SDP7815AZMD
	34333	SG7815AR/883B
5962-88553012A	34333	SG7815AL/883B
	21845	SDP7815A2MD
	<u>3</u> /	OM1815N2/883B
5962-88553014A	<u>3</u> /	OM1815SRM
5962-88553015A	<u>3</u> /	OM1815N5M
5962F8855301UA	<u>3</u> /	OMR1815STM/883B

<sup>1/</sup> The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.

<sup>2/</sup> Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

<sup>3/</sup> Not available from approved source of supply.

# STANDARD MICROCIRCUIT DRAWING BULLETIN - Continued

Vendor CAGE <u>number</u>	Vendor name and address
U3158	SEMELAB PLC Coventry Road, Lutterworth, Leicestershire LE174JB United Kingdom
21845	Solitron Devices Incorporated 3301 Electronics Way West Palm Beach, FL 33407-4697
34333	Microsemi Integrated Products 11861 Western Avenue Garden Grove, CA 92841-2119

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.